

C1210C369B2TACTU

Aliases (C1210C369B2TAC7800) SMD Comm X8G HT150C, Ceramic, 3.6 pF, +/-0.1 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click here for the 3D model.

| General Information | |
|--------------------------|--|
| Series | SMD Comm X8G HT150C |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable |
| Features | High Temperature, Ultra-Stable |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 30 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|--|
| Capacitance | 3.6 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | +/-0.1 pF |
| Voltage DC | 200 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8G |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 100 GOhms |

 Dimensions

 Chip Size
 1210

 L
 3.2mm +/-0.2mm

 W
 2.5mm +/-0.2mm

 T
 0.78mm +/-0.10mm

 S
 1.5mm MIN

 B
 0.5mm +/-0.25mm

Packaging Specifications

| Packaging | T&R, 180mm, Plastic Tape |
|--------------------|--------------------------|
| Packaging Quantity | 4000 |
| | |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.